

Title (en)  
PLASTIC ENCAPSULATED INTEGRATED CIRCUIT PACKAGE WITH ELECTROSTATIC SHIELD

Publication  
**EP 0300632 A3 19901212 (EN)**

Application  
**EP 88306065 A 19880704**

Priority  
CA 542524 A 19870720

Abstract (en)  
[origin: EP0300632A2] A plastic encapsulated integrated circuit package has a chip (18) secured to the upper surface of a base (16) and is connected to leads (22) which have their lower surfaces in a plane above that of the bottom of the base (16). An electrostatic shield (30) is electrically connected to the bottom of the base (16) and underlies the leads (22) without touching them, to reduce crosstalk. The support for the base (16) is integrally connected by a conductive strip to the lead for the ground pin of the chip (18), to ground the shield (30). The whole is plastic encapsulated. To permit encapsulation, the shield (30) extends towards but stops short of the dam bars (20) for the leads (22).

IPC 1-7  
**H05K 5/06**; **H05K 7/00**; **H05K 1/00**

IPC 8 full level  
**H01L 23/28** (2006.01); **H01L 23/495** (2006.01); **H01L 23/50** (2006.01); **H01L 23/552** (2006.01); **H01L 23/60** (2006.01); **H05K 9/00** (2006.01)

CPC (source: EP US)  
**H01L 23/495** (2013.01 - EP US); **H01L 23/552** (2013.01 - EP US); **H01L 23/60** (2013.01 - EP US); **H01L 24/32** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 2224/2612** (2013.01 - EP); **H01L 2224/32245** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01014** (2013.01 - EP US); **H01L 2924/01025** (2013.01 - US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01076** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/12033** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US)

Citation (search report)  
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• [Y] DE 3410196 A1 19850926 - SIEMENS AG [DE]  
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Designated contracting state (EPC)  
CH DE FR GB IT LI NL

DOCDB simple family (publication)  
**EP 0300632 A2 19890125**; **EP 0300632 A3 19901212**; AU 1913888 A 19890127; CA 1278618 C 19910102; JP H01120041 A 19890512; JP H0563101 B2 19930909; US 4953007 A 19900828

DOCDB simple family (application)  
**EP 88306065 A 19880704**; AU 1913888 A 19880719; CA 542524 A 19870720; JP 18145488 A 19880720; US 26064088 A 19881021